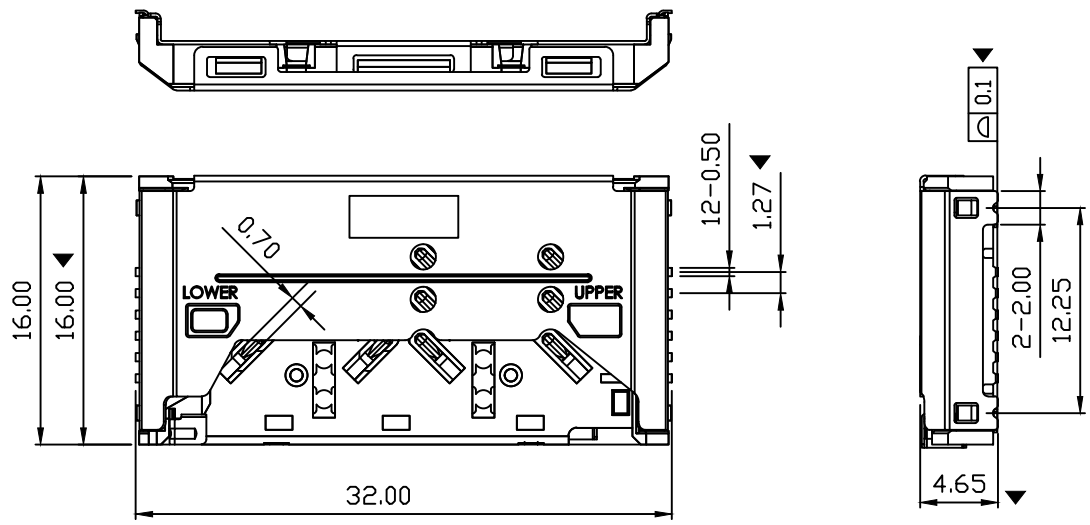


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2011/12/31



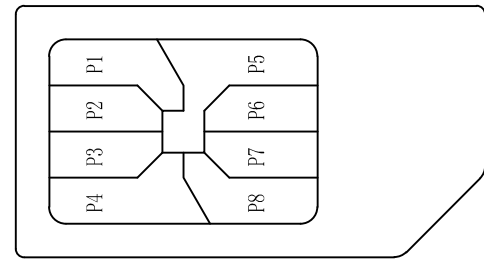
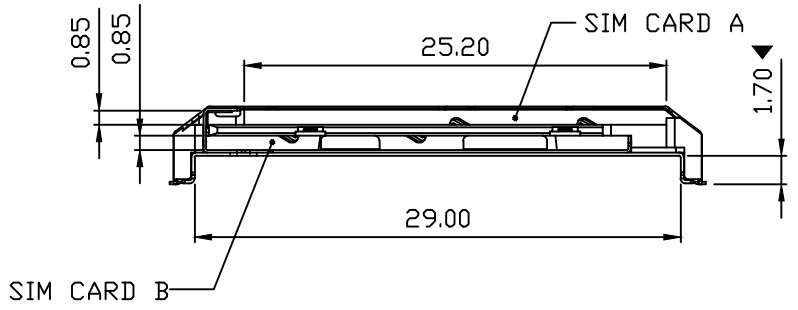
NOTES:

1.MATERIAL:
 HOUSING:HI-TEMP.PLASTIC,BLACK,UL 94V-0
 CONTACT:COPPER ALLOY,T=0.15mm.
 SHEEL A:COPPER ALLOY,T=0.20mm.
 SHEEL B:STAINLESS STEEL,T=0.20mm.
 LOCK: STAINLESS STEEL,T=0.15mm

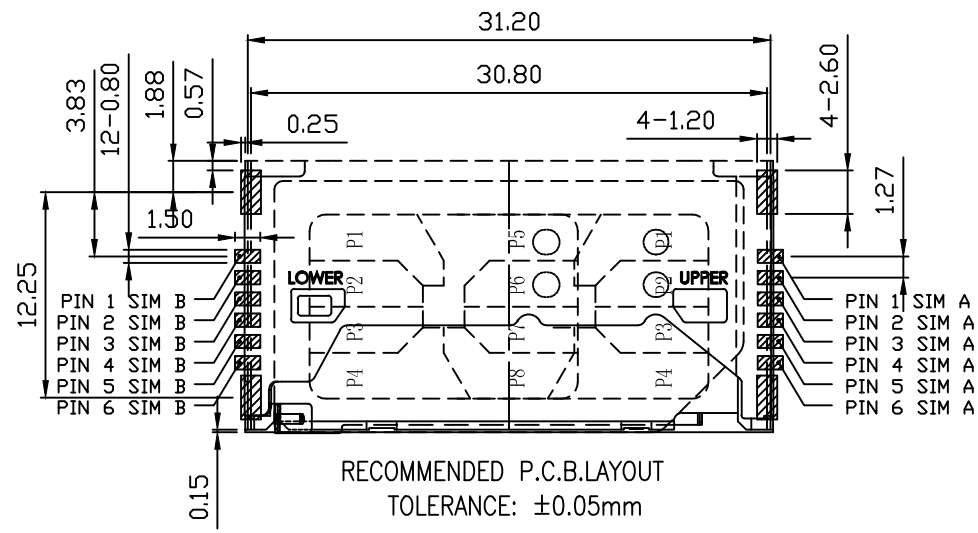
2.FINISH:

CONTACT:50u" MIN Ni UNDERPLATING OVERALL.
 GOLD FLASH OVER PLATING ON CONTACT AND SOLDER AREA.
 SHEEL A :50u" MIN Ni UNDERPLATING OVERALL,
 1U" AU PLATING SOLDER AREA.

3.ALL DIMENSIONS MARKED ▼ MUST BE CONTROLLED BY QC.



P1	:	VCC
P2	:	RST
P3	:	CLK
P4	:	RESERVED
P5	:	GND
P6	:	VPP
P7	:	I / O
P8	:	RESERVED



PIN NO.	DESCPTION	PIN NO.	DESCPTION
SIM CARD A PIN 1	GND	SIM CARD B PIN 1	GND
SIM CARD A PIN 2	VCC	SIM CARD B PIN 2	VCC
SIM CARD A PIN 3	VPP	SIM CARD B PIN 3	VPP
SIM CARD A PIN 4	RST	SIM CARD B PIN 4	RST
SIM CARD A PIN 5	I/O	SIM CARD B PIN 5	I/O
SIM CARD A PIN 6	CLK	SIM CARD B PIN 6	CLK

GENERAL TOLERANCE	DWG NO.	JYSA0705-002	APPD:	WIND	Scale	1:1
X.±0.25	x.±5'	Title	4.70H 二合一 卡座	CHKD:	UNIT	mm
.X±0.20	.x'±2'		SMT CONN	DR:		
.XX±0.15	.xx'±1'	Part NO.	JYS-SIM470-060	Date		2014/02/22
.XXX±0.08	.xxx'±0.5'					
SHEET 1/1						

杰宇森电子有限公司
 JIE YU SEN ELECTRONIC CO., LTD.